MA24D50

Silicon epitaxial planar type

For rectification

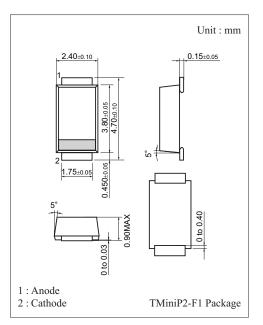
■ Features

- Forward current (Average) $I_{F(AV)} = 3.0 \text{ A}$ rectification is possible
- Low forward voltage V_F

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V_R	40	V	
Maximum peak reverse voltage	V _{RM}	40	V	
Forward current (Average) *1	I _{F(AV)}	3.0	A	
Non-repetitive peak forward surge current *2	I _{FSM}	60	A	
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-40 to +150	°C	

Note) *1: Mounted on an alumina PC board

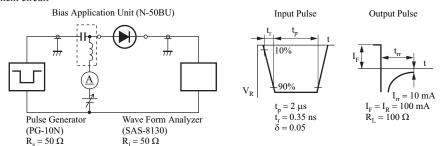


Marking Symbol: 5R

■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 3.0 A$		0.46	0.51	V
Reverse current	I_R	$V_R = 40 V$		40	200	μА
Terminal capacitance	Ct	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		105		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}, I_{rr} = 10 \text{ mA},$ $R_L = 100 \Omega$		33		ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. *: t_{rr} measurement circuit



^{*2: 50} Hz sine wave 1 cycle (Non-repetitive peak current)

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